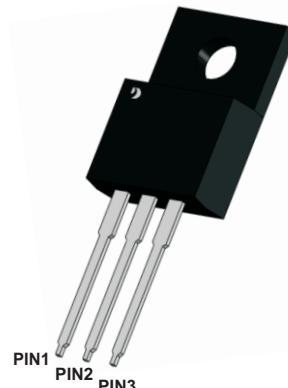




2A, 600V N-CHANNEL POWER MOSFET

ITO-220ABW



DESCRIPTION

The F2N60 is a high voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in switching power supplies and adaptors.

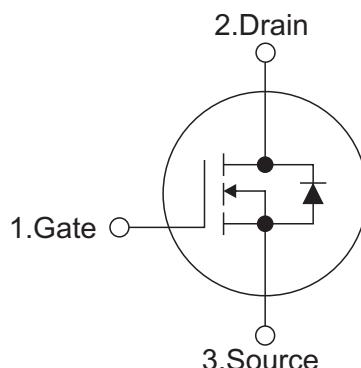
Features

- $R_{DS(ON)} \leq 4 \Omega$ @ $V_{GS}=10V$, $I_D=1A$
- Fast switching capability
- Avalanche energy tested
- Improved dv/dt capability, high ruggedness

Mechanical data

- Case: ITO-220ABW
- Approx. Weight: 2.1g (0.07oz)
- Lead free finish, RoHS compliant
- Case Material: "Green" molding compound, UL flammability classification 94V-0, "Halogen-free".

SYMBOL



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$, unless otherwise specified)

PARAMETER	Symbols	RATINGS	Units
Drain-Source Voltage	V_{DSS}	600	V
Gate-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current	I_D	2	A
		1.4	A
Pulsed Drain Current (Note 2)	I_{DM}	8	A
Avalanche Energy Single Pulsed (Note 3)	E_{AS}	140	mJ
Peak Diode Recovery dv/dt (Note 4)	dv/dt	2.1	V/ns
Power Dissipation	P_D	43	W
Operation Junction Temperature and Storage Temperature	T_j, T_{stg}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. L = 30mH, IAS = 3.1A, VDD = 50V, RG = 25 Ω, Starting TJ = 25°C

4. ISD ≤ 10A, di/dt ≤ 200A/μs, VDD ≤ BVDSS, Starting TJ = 25°C

THERMAL DATA

PARAMETER	Symbols	RATINGS	Units
Junction to Ambient	R_{thJA}	63	°C/W
Junction to Case	R_{thJC}	2.9	°C/W



ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

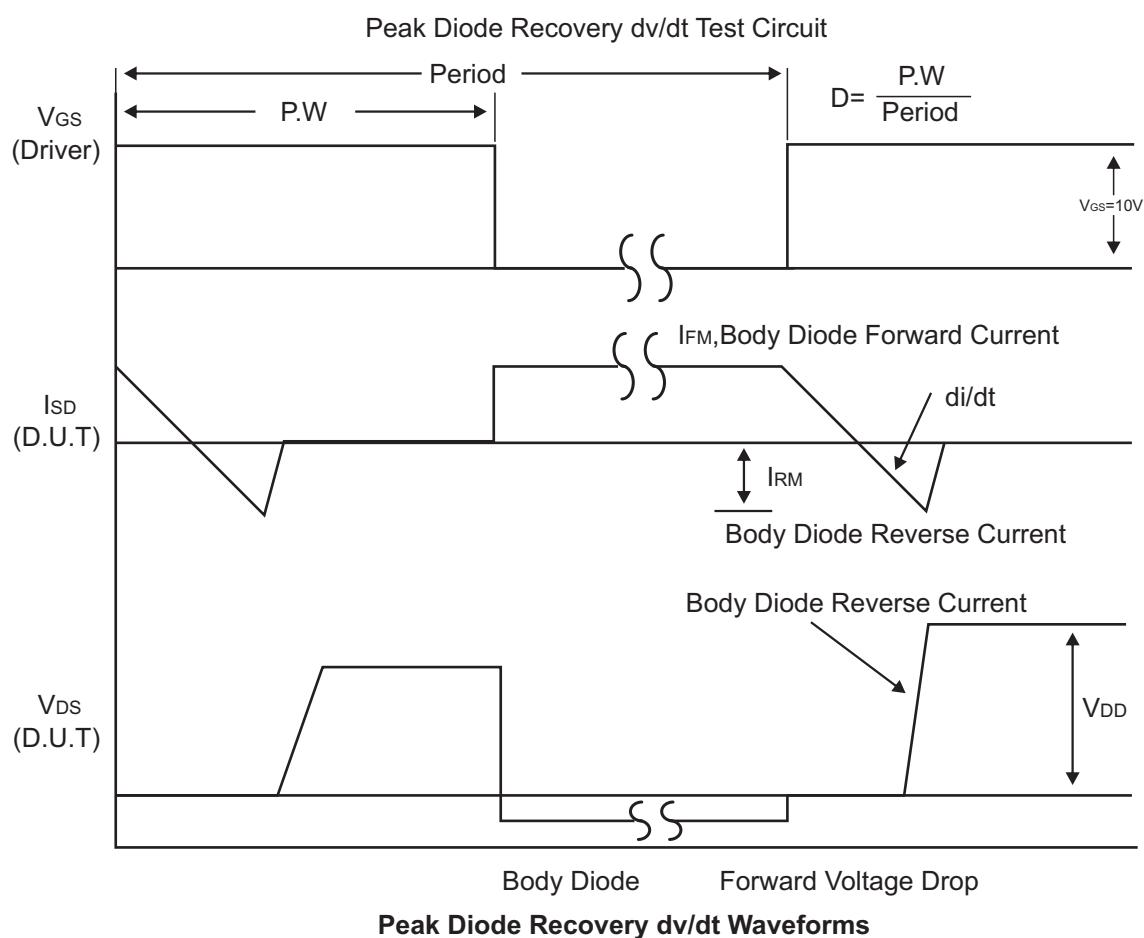
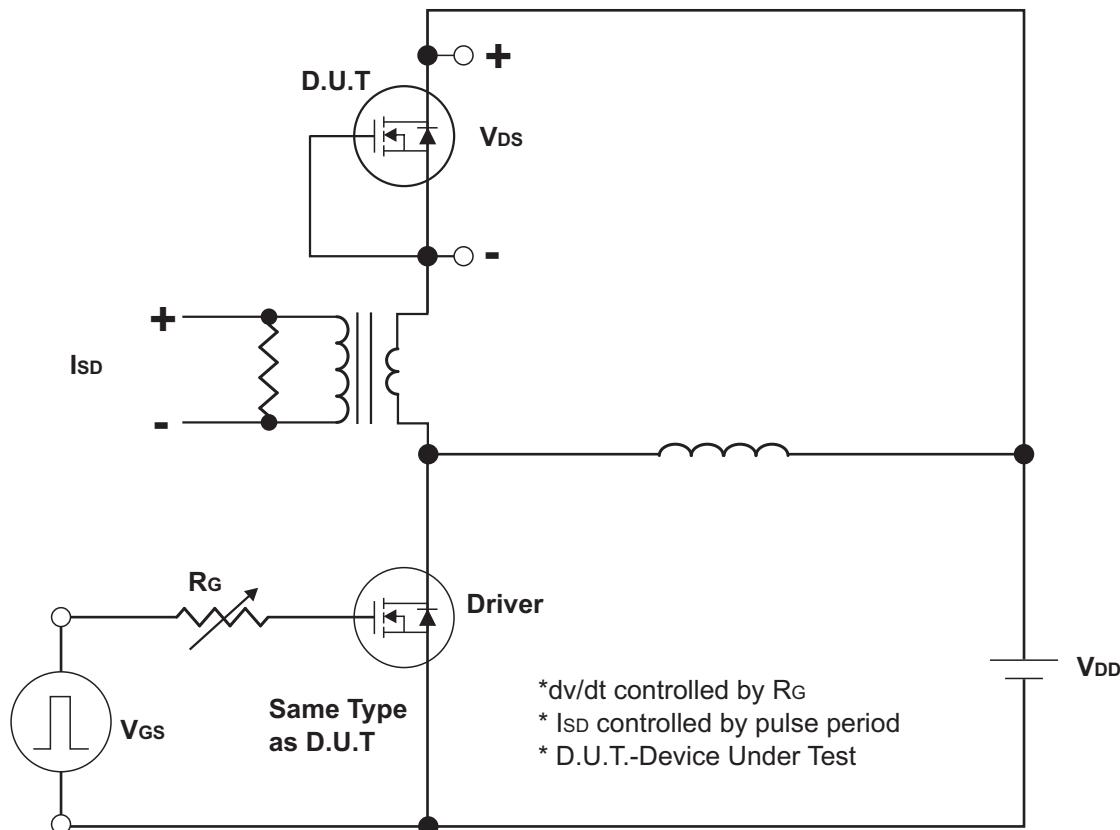
PARAMETER	Symbols	TEST CONDITIONS	Min	Typ	Max	Units
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$			1	μA
Gate- Source Leakage Current	Forward	$V_{GS}=30V, V_{DS}=0V$			100	nA
	Reverse	$V_{GS}=-30V, V_{DS}=0V$			-100	
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.0A$		3.4	4.0	Ω
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	$V_{DS}=25V,$ $V_{GS}=0V,$ $f=1.0MHz$		564		pF
Output Capacitance	C_{oss}			66		pF
Reverse Transfer Capacitance	C_{rss}			12		pF
SWITCHING CHARACTERISTICS						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=480V, V_{GS}=10V,$ $I_D=2A, I_G=1mA$ (NOTE1,2)		13		nC
Gate-Source Charge	Q_{GS}			4		nC
Gate-Drain Charge	Q_{GD}			2.2		nC
Turn-On Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=100V, V_{GS}=10V,$ $I_D=2A, R_G=25\Omega$ (NOTE1,2)		7		ns
Turn-On Rise Time	t_R			16		ns
Turn-Off Delay Time	$t_{D(OFF)}$			36		ns
Turn-Off Fall Time	t_F			22		ns
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Maximum Body-Diode Continuous Current	I_S				2	A
Maximum Body-Diode Pulsed Current	I_{SM}				8	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_S=2A, V_{GS}=0V$			1.4	V
Reverse Recovery Time (Note 1)	trr	$I_S=2A, V_{GS}=0V,$ $di/dt=100A/\mu s$		250		ns
Reverse Recovery Charge	Qrr			4.5		μC

Notes:

1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
2. Essentially independent of operating temperature.

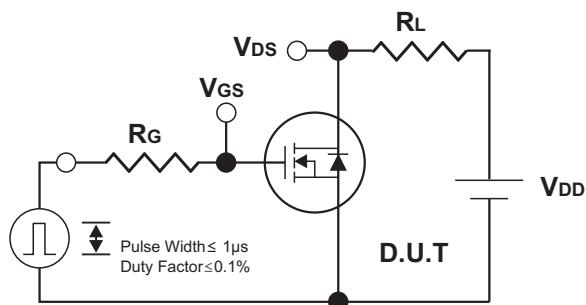


Test Circuits and waveforms

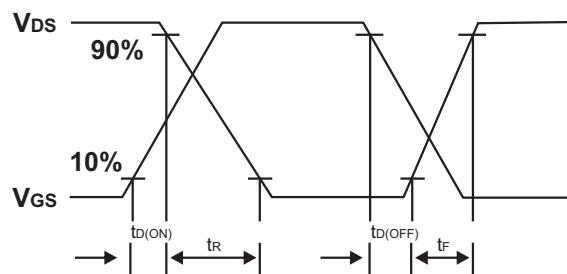




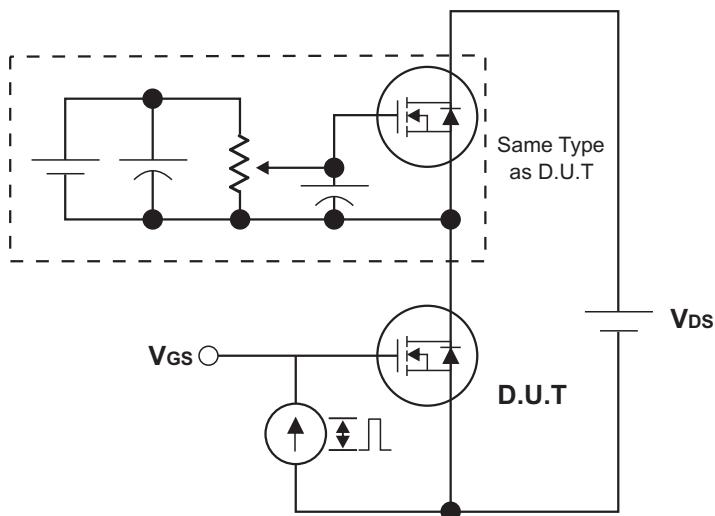
Test Circuits and waveforms



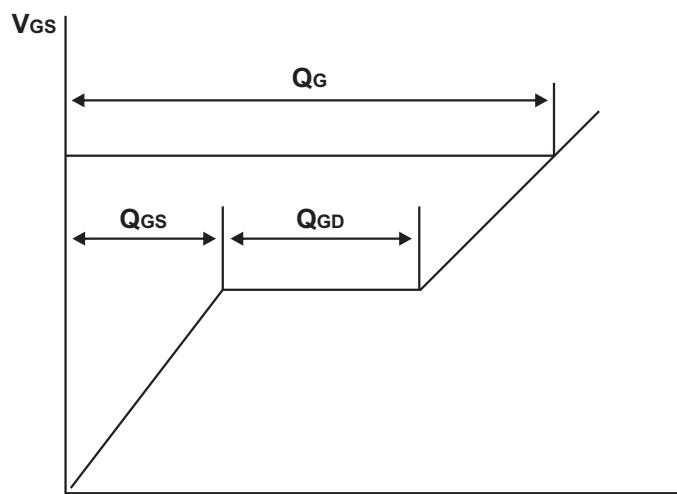
Switching Test Circuit



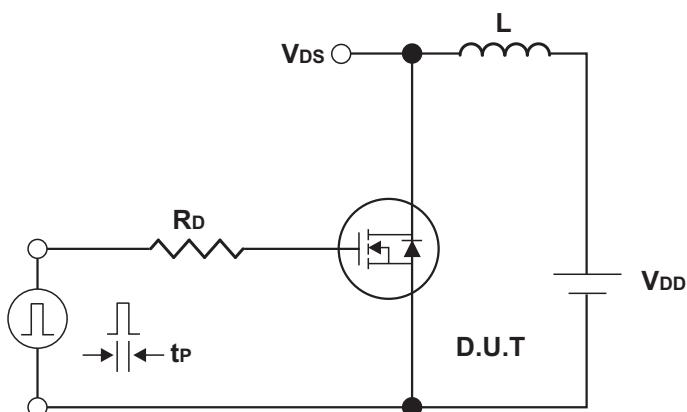
Switching Waveforms



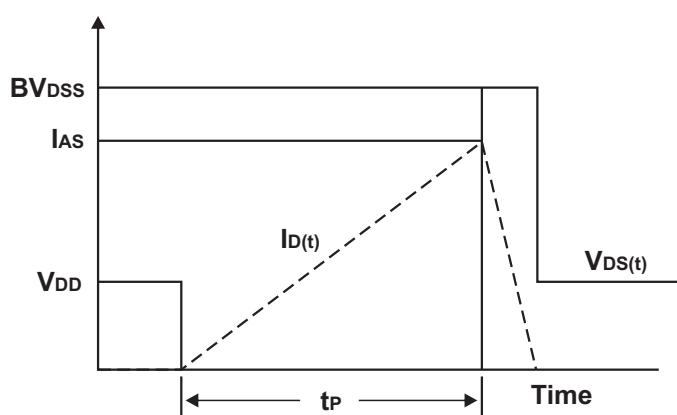
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



Typical Characteristics

Fig.1 Drain Current vs. Gate-Source Voltage

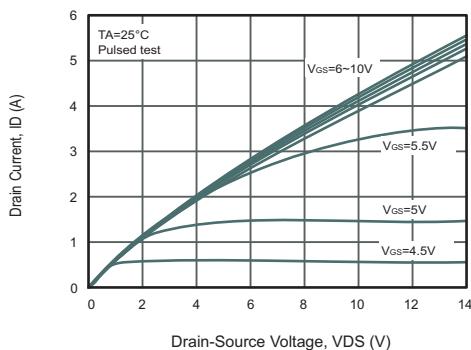


Fig.2 Drain-Source On-Resistance vs. Gate-Source Voltage

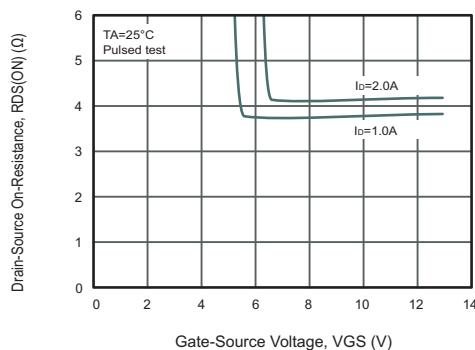


Fig.3 Gate Charge Characteristics

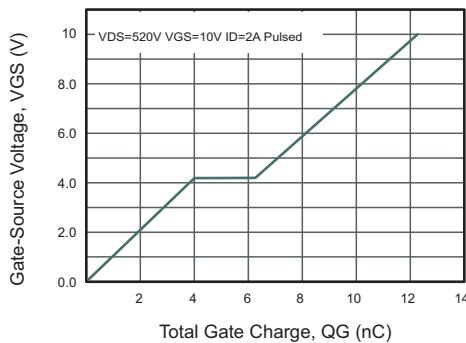


Fig.4 Capacitance Characteristics

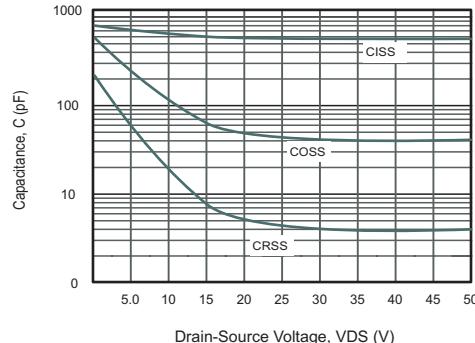


Fig.5 Drain-Source On-Resistance vs. Junction Temperature

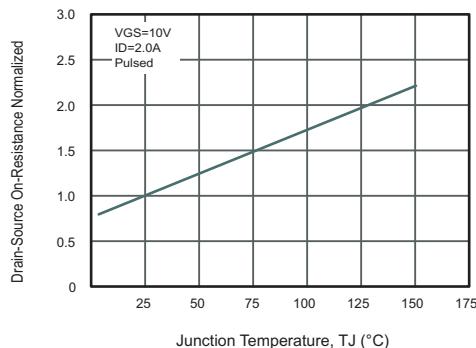


Fig.6 Breakdown Voltage vs. Junction Temperature

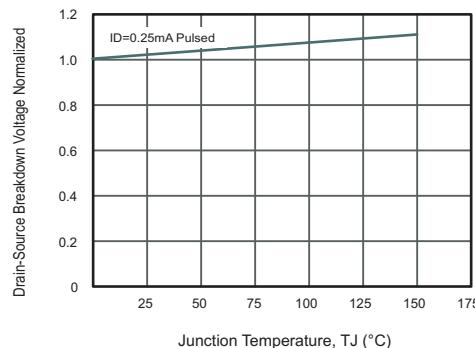


Fig.7 Gate Threshold Voltage vs. Junction Temperature

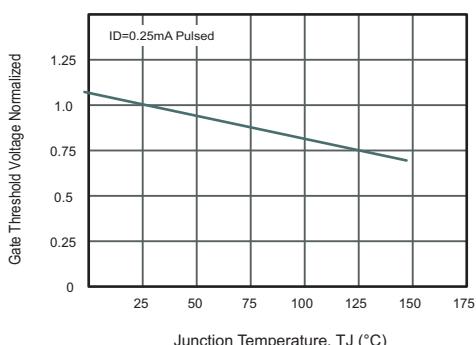
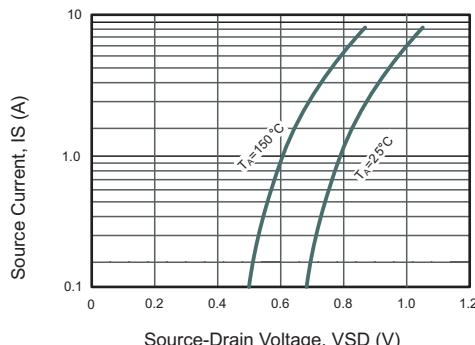


Fig.8 Source Current vs. Source-Drain Voltage





Typical Characteristics

Fig.9 Drain Current vs. Gate-Source Voltage

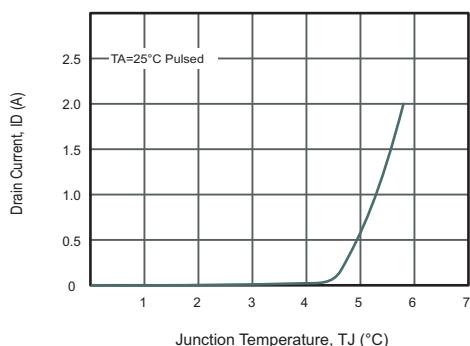


Fig.10 Drain-Source On-Resistance vs. Drain Current

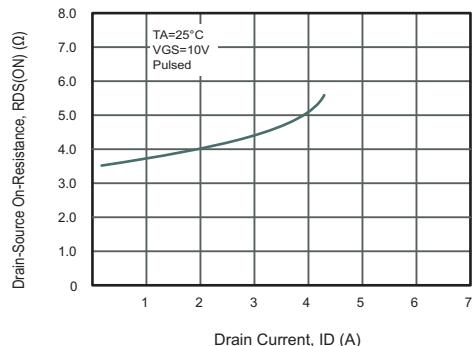


Fig.11 Drain Current vs. Junction Temperature

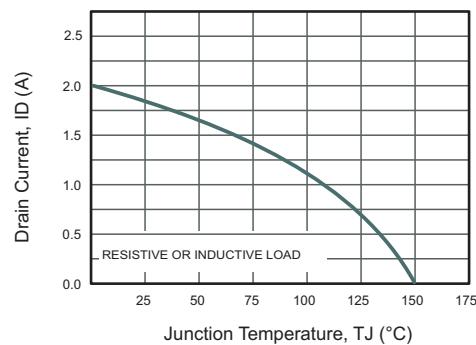


Fig.12 Power Dissipation vs. Junction Temperature

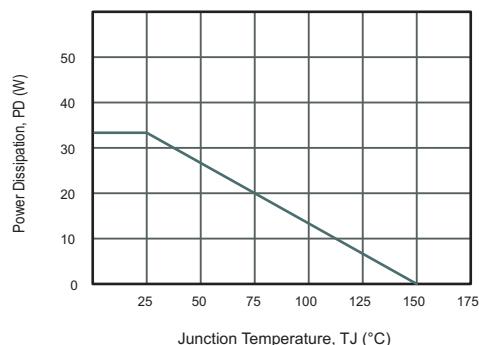
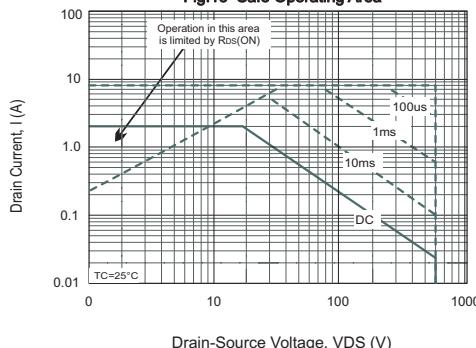


Fig.13 Safe Operating Area

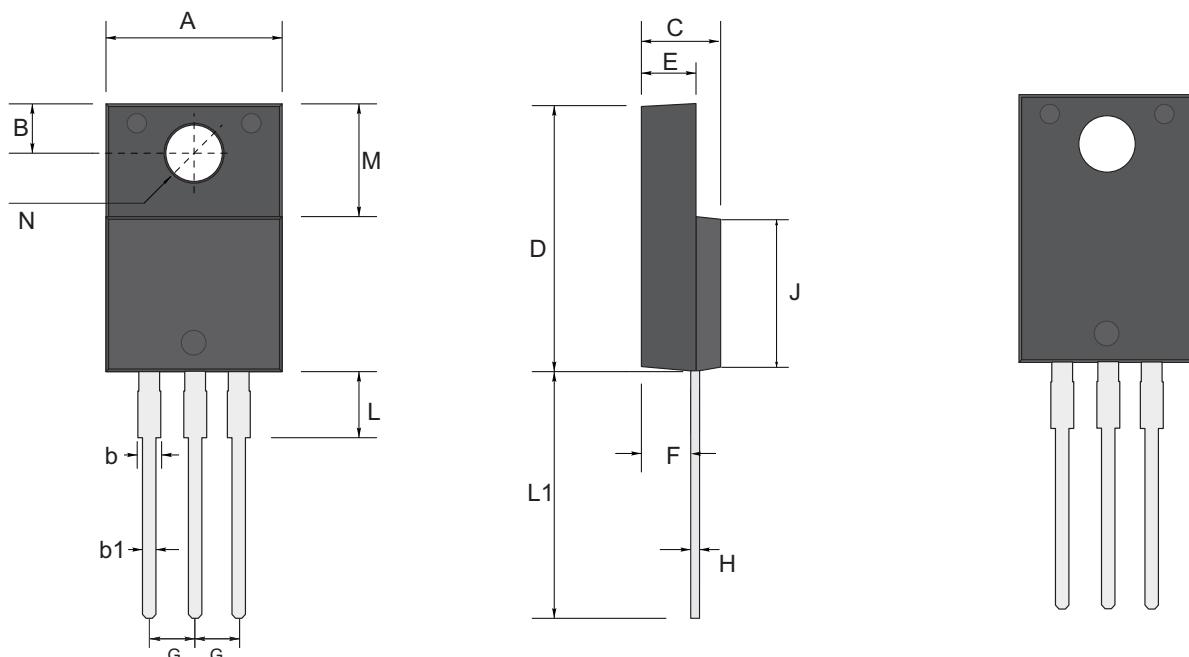




PACKAGE OUTLINE

Plastic Through hole package; 3 leads

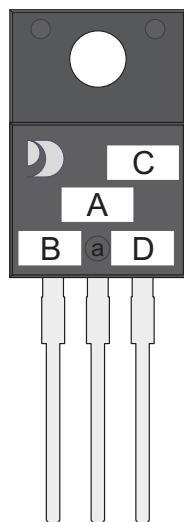
ITO-220ABW



ITO-220ABW mechanical data

UNIT	A	B	b	b1	C	D	E	F	G	H	L	L1	M	N
mm	max	10.5	2.85	1.4	0.8	4.7	16.0	2.9	2.8	2.54 TYPICAL	0.70	2.9	14.3	7.0
	typ	10.0	2.70	1.2	0.6	4.5	15.0	2.7	2.7		0.55	2.5	13.5	6.8
	min	9.85	2.54	1.1	0.5	4.4	14.7	2.5	2.5		0.41	2.3	13.0	6.3
mil	max	413	112	55	31	185	630	114	110	100 TYPICAL	27	114	563	276
	typ	394	106	47	24	177	590	106	106		22	98	531	267
	min	388	100	43	20	173	580	98	98		16	91	512	248

MARKING DIAGRAM



- Unmarkable Surface
- Marking Composition Field
- a:Ejector Pin Mark
- A:Marking Area
- B: Lot Code
- C: Additional Information
- D:Date Code (YWW)
- Y:Years(0~9)
- WW:Week



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